

UNITED STATES PATENT AND TRADEMARK OFFICE  
**CERTIFICATE OF CORRECTION**

PATENT NO. : 7,041,533 B1  
APPLICATION NO. : 09/590621  
DATED : May 9, 2006  
INVENTOR(S) : Salman Akram and Syed Sajid Ahmad

Page 1 of 2

It is certified that error appears in the above-identified patent and that said Letters Patent is hereby corrected as shown below:

**On the title page:**

ITEM (57) **ABSTRACT**

change "face-down" to --face down--

**In the specification:**

COLUMN 1, LINE 47,	change "state-of-the-art" to --state of the art--
COLUMN 2, LINE 3,	change "solder bumps 220A." to --conductor structures 220A, such as solder bumps.--
COLUMN 2, LINE 4,	change "solder bumps 220" to --conductor structures 220, such as solder bumps,--
COLUMN 2, LINE 24,	change "face-down" to --face down--
COLUMN 2, LINE 28,	after "along" and before "central" insert --the--
COLUMN 2, LINE 32,	change "face-down" to --face down--
COLUMN 2, LINES 66-67,	change "solder bumps 220." to --conductor structures 220, 220A.--
COLUMN 2, LINE 67,	change "solder bumps 220" to --conductor structures 220, such as solder bumps,--
COLUMN 3, LINE 2,	change "solder bumps 220" to --conductor structures 220, such as solder bumps,--
COLUMN 3, LINE 5,	change "bumps 220" to --conductor structures 220--
COLUMN 3, LINE 9,	change "active" to --active surface 204 and--
COLUMN 3, LINE 9,	change "solder bumps 220" to --conductor structures 220, such as solder bumps,--
COLUMN 3, LINE 20,	change "solder bumps 220" to --conductor structures 220, such as solder bumps,--
COLUMN 3, LINES 27-28,	change "solder bumps 220 or other conductive structures" to --conductor structures 220, such as solder bumps--
COLUMN 3, LINES 30-31,	change "solder bumps 220" to --conductor structures 220, such as solder bumps,--
COLUMN 3, LINE 32,	change "other" to --others--
COLUMN 3, LINE 33,	change "well known" to --well-known--
COLUMN 3, LINE 45,	change "edge, 226, 228, thereof" to --edge 226, 228 thereof--
COLUMN 3, LINES 47-48,	change "conductive structures such as solder bumps 220," to --conductor structures 220, such as solder bumps,--
COLUMN 3, LINES 58-59,	change "solder bumps 220" to --conductor structures 220A, such as solder bumps,--

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**In the specification (continued):**

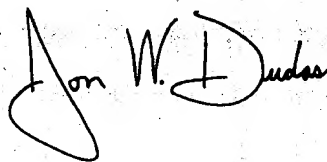
COLUMN 4, LINE 48,	change "previously-formed" to --previously formed--
COLUMN 5, LINE 26,	change "inventor's" to --inventors'--
COLUMN 5, LINE 50,	change "face-down" to --face down--
COLUMN 11, LINE 63,	after "stabilizers 50" and before "in situ" delete "can be fabricated"
COLUMN 11, LINE 64,	after "device 10" and before "or" insert --or test substrate,--
COLUMN 13, LINE 3,	change "122. Such" to --122 (FIG. 21). Such--
COLUMN 14, LINE 14,	after "equal to" and before "thickness" insert --the--
COLUMN 15, LINE 38,	after "86" and before "cure" insert --to--
COLUMN 15, LINE 56,	change "optics and scan controller 94" to --mirror 94--
COLUMN 16, LINE 10,	change "Checkpoints" to --Checkpoint@-
COLUMN 18, LINE 7,	after "surface level 88," and before "and" insert --88A, 88B--
COLUMN 18, LINE 29,	change "stabilizers 122" to --base supports 122--
COLUMN 18, LINE 54,	after "shown" and before "in broken" insert --in FIG. 20--

**In the claims:**

COLUMN 20, LINE 22,	change "high-level" to --higher-level--
COLUMN 21, LINE 46,	before "die" delete "device"

Signed and Sealed this

Thirteenth Day of November, 2007



JON W. DUDAS  
*Director of the United States Patent and Trademark Office*